

Part Number: XZM2DG81FS

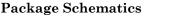
2.8 x 0.8 mm Right Angle SMD Chip LED Lamp

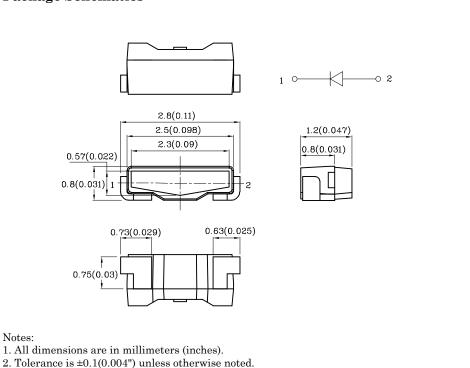
- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2,000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- Halogen-free
- RoHS compliant





ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES





. Tolerance is $\pm 0.1(0.004^{\circ})$ unless otherwise noted.

3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)	Green (InGaN)	Unit		
Reverse Voltage	VR	5	V	
Forward Current	$I_{\rm F}$	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	100	mA	
Power Dissipation	\mathbf{P}_{D}	120	mW	
Operating Temperature	$T_{\rm A}$	$-40 \sim +85$	°C	
Storage Temperature	Tstg	-40 ~ +85		
Electrostatic Discharge Threshold (HBM)	450	V		

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T _A =25°C)		Green (InGaN)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	$V_{\rm F}$	3.2	V	
Forward Voltage (Max.) (I _F =20mA)	V_{F}	4	V	
Reverse Current (Max.) (V _R =5V)	I_R	50	μΑ	
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λP	520*	nm	
Wavelength of Dominant EmissionCIE127-2007* (Typ.) (I _F =20mA)	λD	525*	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle \lambda$	35	nm	
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	100	pF	

Part Number	Emitting Color	Emitting Material	Lens-color	CIE127 (I _F =2		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XZM2DG81FS	Green	InGaN	Water Clear	1000*	1395*	520*	110°

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Mar 01,2023

XDSB5695 V7-Z Layout: Maggie L.



Handling Precautions

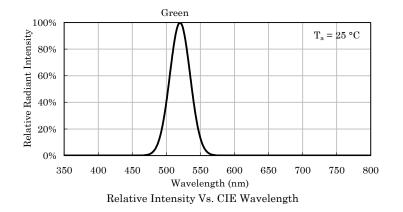
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

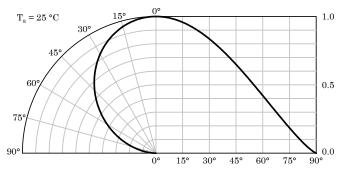
1.Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



2. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

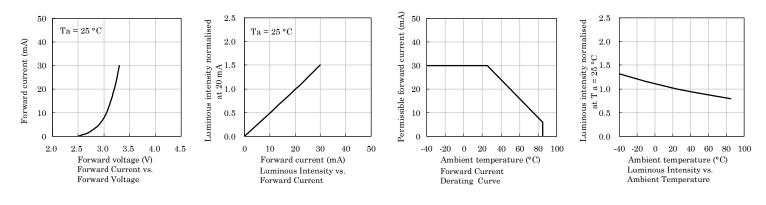




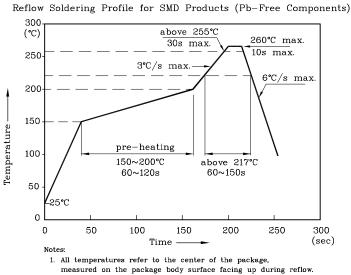


Spatial Distribution

Green



LED is recommended for reflow soldering and soldering profile is shown below.



2. Do not apply any stress to the LED during high temperature conditions 3. Maximum number of soldering passes: 2

XDSB5695 V7-Z Layout: Maggie L.



✤ The device has a single mounting surface. The device must be mounted according to the specifications.

Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)

1.4

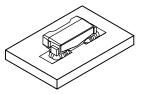
0.5

0.2

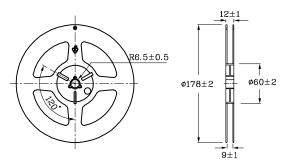
1.4

0.5

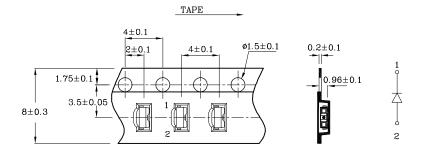
0.9



Reel Dimension (Units : mm)



Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

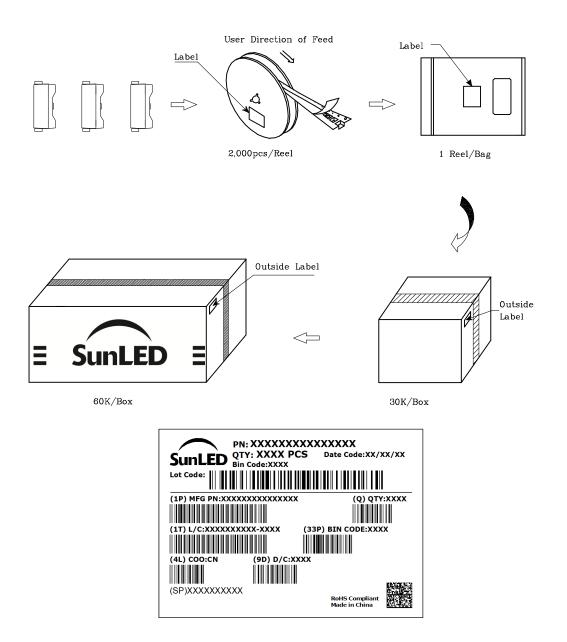
2. Luminous intensity / luminous flux: +/-15\%

3. Forward Voltage: +/-0.1V $\,$

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS



TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please
- consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The performance of the product(s) should be evaluated and verified by the customer to ensure it can meet the customer's application requirements.
- 6. The contents within this document may not be altered without prior consent by SunLED.
- $7. \ Additional \ technical \ notes \ are \ available \ at \ \underline{https://www.SunLEDusa.com/TechnicalNotes.asp}$